- 1. (Currently Amended) A method of forming a layered polishing pad comprising:
  - a) forming a first double-sided adhesive layer on a bottom surface of a subpad, the first double-sided adhesive layer can create stresses that result in curling of the subpad;
  - b) forming a second double-sided adhesive layer on a top surface of the subpad, the second double-sided adhesive layer can create stresses that result in curling of the subpad;
  - c) providing a polishing pad layer having a lower surface; and
  - d) adhering the polishing pad layer to the subpad, the subpad including the second doublesided adhesive layer, by pressing the polishing pad layer lower surface against the second adhesive layer.
- 2. (Currently Amended) The method of claim 1, further including after act b) therein:
  - a) forming an opening that extends through the first adhesive layer, the subpad and the second adhesive layer;
  - b) providing the polishing pad layer with a window, and
  - c) in said the adhering, aligning the window to the opening.
- 3. (Original) The method of claim 1, wherein forming the first and second double-sided adhesive layers includes laminating the first and second double-sided adhesive layers as pressure-sensitive adhesive (PSA) layers to the bottom and top surfaces of the subpad, respectively.
- 4. (Original) The method of claim 1, including respectively providing material for the subpad and the first and second double-sided adhesive layers in roll-good form.
- 5. (Original) The method of claim 1, wherein the acts therein are carried out in the order presented.
- 6. (Currently Amended) A method of forming a layered polishing pad, comprising:

- a) laminating a first double-sided adhesive layer onto a bottom surface of a subpad, the first double-sided adhesive layer can create stresses that result in curling of the subpad;
- b) laminating a second double-sided adhesive layer on a top surface of the subpad, the second double-sided adhesive layer can create stresses that result in curling of the subpad;
- c) forming an opening through the first adhesive layer, the subpad and the second adhesive layer; and
- d) securing a polishing pad having a window formed therein, to the subpad with the second adhesive layer, such that the window is aligned to the opening.
- 7. (Original) The method of claim 6, including providing respective materials for the subpad, the first double-sided adhesive layer and the second double-sided adhesive layer in roll-good form.
- 8. (Original) The method of claim 6, wherein act b) is performed before act c) and wherein laminating the second double sided adhesive layer to the subpad includes:
  - feeding the subpad material and the first double-sided adhesive layer material through nip-rollers to form a laminated structure; and
  - b) maintaining the laminated structure exiting the nip rollers substantially horizontally for a travel length sufficient for the laminated structure to cure.
- 9. (Currently Amended) A method of forming a layered polishing pad comprising:
  - a) sequentially forming respective <u>double-sided</u> adhesive layers on opposing surfaces of a subpad to form a double-laminated subpad, the <u>double-sided</u> adhesive layers can create stresses that result in curling of the <u>double-laminated</u> subpad;
  - b) forming an opening through the double-laminated subpad; and
  - c) securing a polishing pad having a window, to the double-laminated subpad by pressing a polishing pad lower surface against one of the adhesive layers such that the window and opening form a through optical path that includes no adhesive layer.
- 10. (Currently Amended) A method of forming a layered polishing pad comprising:

a) sequentially forming respective <u>double-sided pressure</u> sensitive adhesive layers on opposing surfaces of a subpad to form a double-laminated subpad, the <u>double-sided</u> <u>pressure</u> sensitive <u>adhesive layers can create stresses that result in curling of the double-laminated subpad; and</u>

b) securing a polishing pad to the double-laminated subpad by pressing a polishing pad lower surface against one of the adhesive layers.